

v02.0410

SMT GaAs HBT MMIC DIVIDE-BY-4, DC - 13 GHz

Typical Applications

Prescaler for DC to Ku Band PLL Applications:

- Point-to-Point / Multi-Point Radios
- VSAT Radios
- Fiber Optic
- Test Equipment
- Space & Military

Features

Ultra Low SSB Phase Noise: -151 dBc/Hz

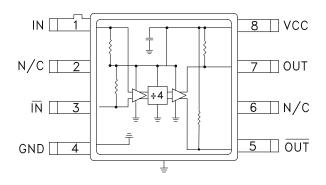
Wide Bandwidth

Output Power: 7 dBm

Single DC Supply: +5V

8 Lead Hermetic SMT Package

Functional Diagram



General Description

The HMC365G8 is a low noise Divide-by-4 Static Divider with InGaP GaAs HBT technology in an 8 lead glass/metal (hermetic) surface mount hermetic package. This device operates from DC (with a square wave input) to 13 GHz input frequency with a single +5V DC supply. The low additive SSB phase noise of -151 dBc/Hz at 100 kHz offset helps the user maintain good system noise performance.

Electrical Specifications, $T_A = +25^{\circ} \text{ C}$, 50 Ohm System, Vcc = 5V

Parameter	Conditions	Min.	Тур.	Max.	Units
Maximum Input Frequency		13	14		GHz
Minimum Input Frequency	Sine Wave Input. [1]		0.2	0.5	GHz
Input Power Range	Fin = 1 to 11 GHz	-15	>-20	+10	dBm
	Fin = 11 to 12 GHz	-10	>-15	+5	dBm
	Fin = 12 to 13 GHz	-5	>-8	0	dBm
Output Power	Fin = 13 GHz	3	7		dBm
Reverse Leakage	Both RF Outputs Terminated		45		dB
SSB Phase Noise (100 kHz offset)	Pin = 0 dBm, Fin = 6 GHz		-151		dBc/Hz
Output Transition Time	Pin = 0 dBm, Fout = 882 MHz		100		ps
Supply Current (Icc)			120		mA

^{1.} Divider will operate down to DC for square-wave input signal.

HMC365G8* PRODUCT PAGE QUICK LINKS

Last Content Update: 07/13/2017

COMPARABLE PARTS 🖳

View a parametric search of comparable parts.

EVALUATION KITS

· HMC365G8 Evaluation Board.

DOCUMENTATION

Data Sheet

• HMC365G8 Data Sheet

REFERENCE MATERIALS 🖵

Quality Documentation

 Semiconductor Qualification Test Report: GaAs HBT-A (QTR: 2013-00228)

DESIGN RESOURCES

- HMC365G8 Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all HMC365G8 EngineerZone Discussions.

SAMPLE AND BUY 🖵

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

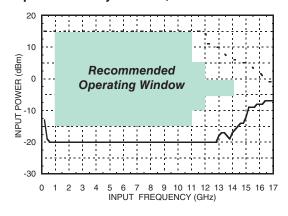
DOCUMENT FEEDBACK 🖳

Submit feedback for this data sheet.

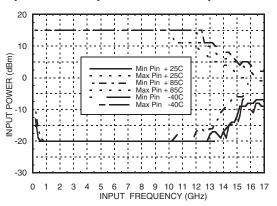


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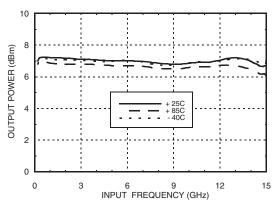
Input Sensitivity Window, T= 25 °C



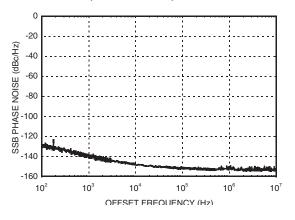
Input Sensitivity Window vs. Temperature



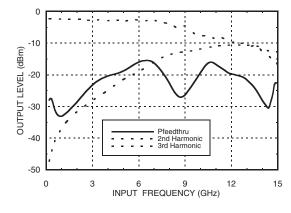
Output Power vs. Temperature



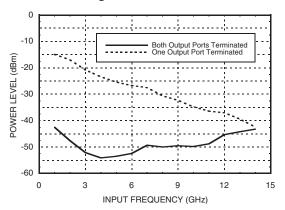
SSB Phase Noise Performance, Pin= 0 dBm, T= 25 °C



Output Harmonic Content, Pin= 0 dBm, T= 25 °C



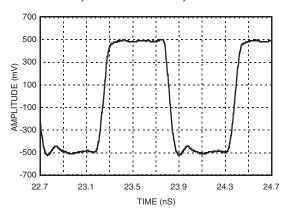
Reverse Leakage, Pin= 0 dBm, T= 25 °C





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Output Voltage Waveform, Pin= 0 dBm, Fout= 882 MHz, T= 25 °C





Absolute Maximum Ratings

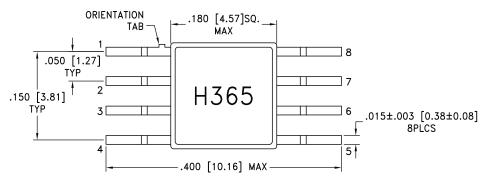
RF Input (Vcc = +5V)	+13 dBm	
Vcc	+5.5V	
Junction Temperature (T _j)	135 °C	
Continuous Pdiss (T = 85 °C) (derate 12.5 mW/° C above 85 °C)	625 mW	
Thermal Resistance (R _{TH}) (junction to ground paddle)	80 °C/W	
Storage Temperature	-65 to -150 °C	
Operating Temperature	-40 to +85 °C	

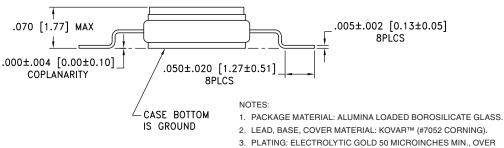
Typical Supply Current vs. Vcc

Vcc (V)	Icc (mA)	
4.75	110	
5.0	120	
5.25	130	

Note: Divider will operate over full voltage range shown above

Outline Drawing





- ELECTROLYTIC NICKEL 50 MICROINCHES MIN.
- 4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 5. TOLERANCES: ±.005 [0.13] UNLESS OTHERWISE SPECIFIED.
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.



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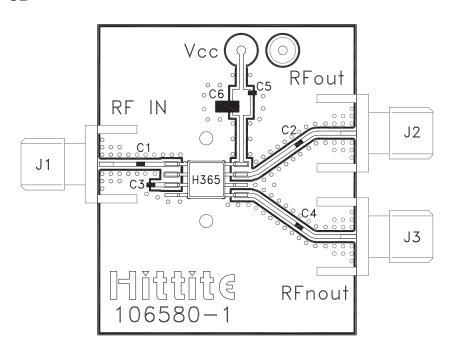
Pin Description

Pin Number	Function	Description	Interface Schematic
1	IN	RF Input must be DC blocked.	Vcc 05V
2, 6	N/C	No connection.	
3	ĪN	RF Input 180° out of phase with pin 1 for differential operation. AC ground for single ended operation.	Vcc ○ 500 IN
4	GND	Ground: Backside of package has exposed metal ground which must be connected to a RF/DC ground.	Ģ GND =
5	ОПТ	Divided output 180° out of phase with pin 7.	Vcc O 5V
7	ОИТ	Divided Output.	Vcc Q 5V
8	VCC	Supply voltage 5V ± 0.25V.	



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Evaluation PCB



List of Materials for Evaluation PCB 106582 [1]

Item	Description	
J1 - J3	PCB Mount SMA RF Connector	
C1 - C4	100 pF Capacitor, 0402 Pkg,	
C5	1000 pF Capacitor, 0603 Pkg.	
C6	10 μF Tantalum Capacitor	
U1	HMC365G8 Divide-by-4	
PCB [2]	106580 Eval Board	

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and backside ground slug should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request. This evaluation board is designed for single ended input testing. J2 and J3 provide differential output signals.



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Application Circuit

